



## LP3943 RGB, White, Blue 16-LED Fun Light Driver

### 1 Features

- Internal Power-On Reset
- Active Low Reset
- Internal Precision Oscillator
- Variable Dim Rates  
(From 6.25 ms to 1.6 s; 160 Hz to 0.625 Hz)
- 16 LED Drivers (Multiple Programmable States: ON, OFF, Input, and Dimming at a Specified Rate)
- 16 Open-Drain Outputs Capable of Driving up to 25 mA per LED

### 2 Applications

- Customized Flashing LED Lights for Cellular Phones
- Portable Applications
- Digital Cameras
- Indicator Lamps
- General Purpose I/O Expander
- Toys

### 3 Description

The LP3943 is an integrated device capable of independently driving 16 LEDs. This device also contains an internal precision oscillator that provides all the necessary timing required for driving each LED. Two prescaler registers, along with two PWM registers, provide a versatile duty-cycle control. The LP3943 contains the ability to dim LEDs in SMBUS/I<sup>2</sup>C applications where it is required, to cut down on bus traffic.

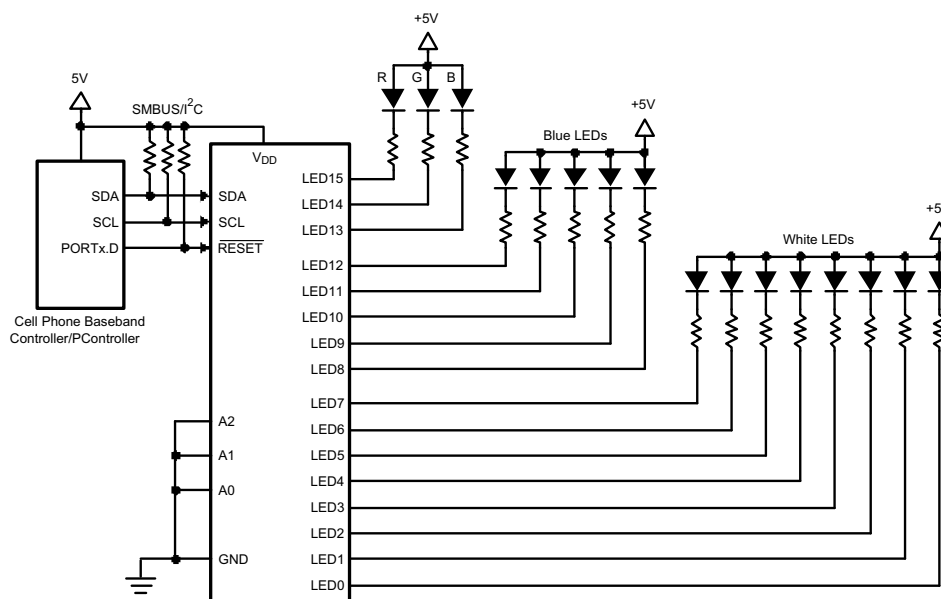
Traditionally, dimming LEDs using a serial shift register such as 74LS594/5 requires a large amount of traffic on the serial bus. The LP3943 instead requires only the setup of the frequency and duty cycle for each output pin; from then on, only a single command from the host is required to turn each individual open drain output to an ON or OFF state, or to cycle a programmed frequency and duty cycle. Maximum output sink current is 25 mA per pin and 200 mA per package. Any ports not used for controlling the LEDs can be used for general purpose input/output expansion.

#### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE   | BODY SIZE (NOM)   |
|-------------|-----------|-------------------|
| LP3943      | WQFN (24) | 4.00 mm × 4.00 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Typical Application Circuit



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## 4 Revision History

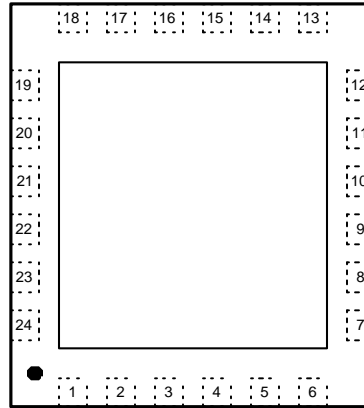
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| <b>Changes from Revision B (September 2013) to Revision C</b>   | <b>Page</b> |
|---|-------------|
| <ul style="list-style-type: none"> <li>Added <i>Device Information</i> and <i>Pin Configuration and Functions</i> sections, <i>ESD Ratings</i> table, <i>Feature Description</i>, <i>Device Functional Modes</i>, <i>Application and Implementation</i>, <i>Power Supply Recommendations</i>, <i>Layout</i>, <i>Device and Documentation Support</i>, and <i>Mechanical, Packaging, and Orderable Information</i> sections. ....</li> </ul> | <b>1</b>    |

| <b>Changes from Revision A (April 2013) to Revision B</b>   | <b>Page</b> |
|---|-------------|
| <ul style="list-style-type: none"> <li>Changed layout of National Data Sheet to TI format; fixed format of Block Diagram .....</li> </ul> | <b>7</b>    |

## 5 Pin Configuration and Functions

**RTW Package  
24-Pin WQFN With Exposed Pad  
Top View**



**Pin Functions**

| PIN    |                         | I/O          | DESCRIPTION                                     |
|--------|-------------------------|--------------|---|
| NUMBER | NAME                    |              |   |
| 1      | LED0                    | Output       | Output of LED0 Driver                           |
| 2      | LED1                    | Output       | Output of LED1 Driver                           |
| 3      | LED2                    | Output       | Output of LED2 Driver                           |
| 4      | LED3                    | Output       | Output of LED3 Driver                           |
| 5      | LED4                    | Output       | Output of LED4 Driver                           |
| 6      | LED5                    | Output       | Output of LED5 Driver                           |
| 7      | LED6                    | Output       | Output of LED6 Driver                           |
| 8      | LED7                    | Output       | Output of LED7 Driver                           |
| 9      | GND                     | Ground       | Ground  |
| 10     | LED8                    | Output       | Output of LED8 Driver                           |
| 11     | LED9                    | Output       | Output of LED9 Driver                           |
| 12     | LED10                   | Output       | Output of LED10 Driver                          |
| 13     | LED11                   | Output       | Output of LED11 Driver                          |
| 14     | LED12                   | Output       | Output of LED12 Driver                          |
| 15     | LED13                   | Output       | Output of LED13 Driver                          |
| 16     | LED14                   | Output       | Output of LED14 Driver                          |
| 17     | LED15                   | Output       | Output of LED15 Driver                          |
| 18     | $\overline{\text{RST}}$ | Input        | Active Low Reset Input                          |
| 19     | SCL                     | Input        | Clock Line for I <sup>2</sup> C Interface       |
| 20     | SDA                     | Input/Output | Serial Data Line for I <sup>2</sup> C Interface |
| 21     | VDD                     | Power        | Power Supply                                    |
| 22     | A0                      | Input        | Address Input 0                                 |
| 23     | A1                      | Input        | Address Input 1                                 |
| 24     | A2                      | Input        | Address Input 2                                 |
| —      | Exposed Pad             | —            | Tie internally to GND pin.                      |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted) <sup>(1)(2)(3)</sup>

|   | MIN                   | MAX | UNIT |
|---|-----------------------|-----|------|
| V <sub>DD</sub>   | −0.5                  | 6   | V    |
| A0, A1, A2, SCL, SDA, $\overline{\text{RST}}$<br>(Collectively called digital pins) |                       | 6   | V    |
| Voltage on LED pins   | V <sub>SS</sub> − 0.5 | 6   | V    |
| Junction temperature  |                       | 150 | °C   |
| Power dissipation <sup>(4)</sup>  |                       | 400 | mW   |
| Storage temperature   | −65                   | 150 | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to the potential at the GND pin.
- (3) If Military/Aerospace specified devices are required, contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (4) The part cannot dissipate more than 400 mW.

### 6.2 ESD Ratings

|  |  | VALUE | UNIT |
|--|--|-------|------|
| V <sub>(ESD)</sub> Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2000 | V    |
|  | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±1000 |      |
|  | Machine model  | ±200  |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted) <sup>(1)(2)</sup>

|                               | MIN | NOM | MAX | UNIT |
|-------------------------------|-----|-----|-----|------|
| V <sub>DD</sub>               | 2.3 |     | 5.5 | V    |
| Junction temperature          | −40 |     | 125 | °C   |
| Operating ambient temperature | −40 |     | 85  | °C   |

- (1) *Absolute Maximum Ratings* are limits beyond which damage to the device might occur. *Recommended Operating Conditions* are conditions under which operation of the device is ensured. *Recommended Operating Conditions* do not imply ensured performance limits. For verified performance limits and associated test conditions, see [Electrical Characteristics](#).
- (2) All voltages are with respect to the potential at the GND pin.

### 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |  | LP3943     | UNIT |
|-------------------------------|--|------------|------|
|                               |  | RTW (WQFN) |      |
|                               |  | 24 PINS    |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance | 37         | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

Unless otherwise noted,  $V_{DD} = 5.5\text{ V}$ . Typical values and limits apply for  $T_J = 25^\circ\text{C}$ . Minimum and maximum limits apply over the entire junction temperature range for operation,  $T_J = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ .<sup>(1)</sup>

| PARAMETER  |   | TEST CONDITIONS   | MIN         | TYP | MAX         | UNIT          |
|--|---|---|-------------|-----|-------------|---------------|
| <b>POWER SUPPLY</b>                                |   |   |             |     |             |               |
| $V_{DD}$   | Supply voltage                          |   | 2.3         | 5   | 5.5         | V             |
| $I_Q$  | Supply current                          | No load   |             | 350 | 550         | $\mu\text{A}$ |
|  |   | Standby   |             | 2   | 5           |               |
| $\Delta I_Q$                                       | Additional standby current              | $V_{DD} = 5.5\text{ V}$ , every LED pin at 4.3 V            |             |     | 2           | mA            |
| $V_{POR}$  | Power-On Reset voltage                  |   |             | 1.8 | 1.96        | V             |
| $t_w$  | Reset pulse width                       |   |             | 10  |             | ns            |
| <b>LED</b>   |   |   |             |     |             |               |
| $V_{IL}$   | Low level input voltage                 |   | -0.5        |     | 0.8         | V             |
| $V_{IH}$   | High level input voltage                |   | 2           |     | 5.5         | V             |
| $I_{OL}$   | Low level output current <sup>(2)</sup> | $V_{OL} = 0.4\text{ V}$ , $V_{DD} = 2.3\text{ V}$           | 9           |     |             | mA            |
|  |   | $V_{OL} = 0.4\text{ V}$ , $V_{DD} = 3\text{ V}$             | 12          |     |             |               |
|  |   | $V_{OL} = 0.4\text{ V}$ , $V_{DD} = 5\text{ V}$             | 15          |     |             |               |
|  |   | $V_{OL} = 0.7\text{ V}$ , $V_{DD} = 2.3\text{ V}$           | 15          |     |             |               |
|  |   | $V_{OL} = 0.7\text{ V}$ , $V_{DD} = 3\text{ V}$             | 20          |     |             |               |
|  |   | $V_{OL} = 0.7\text{ V}$ , $V_{DD} = 5\text{ V}$             | 25          |     |             |               |
| $I_{LEAK}$   | Input leakage current                   | $V_{DD} = 3.6\text{ V}$ , $V_{IN} = 0\text{ V}$ or $V_{DD}$ | -1          |     | 1           | $\mu\text{A}$ |
| $C_{I/O}$  | Input/output capacitance                | See <sup>(3)</sup>  |             | 2.6 | 5           | pF            |
| <b>ALL DIGITAL PINS (EXCEPT SCL AND SDA PINS)</b>  |   |   |             |     |             |               |
| $V_{IL}$   | LOW level input voltage                 |   | -0.5        |     | 0.8         | V             |
| $V_{IH}$   | HIGH level input voltage                |   | 2           |     | 5.5         | V             |
| $I_{LEAK}$   | Input leakage current                   |   | -1          |     | 1           | $\mu\text{A}$ |
| $C_{IN}$   | Input capacitance                       | $V_{IN} = 0\text{ V}$ <sup>(3)</sup>                        |             | 2.3 | 5           | pF            |
| <b>I<sup>2</sup>C INTERFACE (SCL AND SDA PINS)</b> |   |   |             |     |             |               |
| $V_{IL}$   | LOW level input voltage                 |   | -0.5        |     | $0.3V_{DD}$ | V             |
| $V_{IH}$   | HIGH level input voltage                |   | $0.7V_{DD}$ |     | 5.5         | V             |
| $V_{OL}$   | LOW level output voltage                |   | 0           |     | $0.2V_{DD}$ | V             |
| $I_{OL}$   | LOW level output current                | $V_{OL} = 0.4\text{ V}$                                     | 3           | 6.5 |             | mA            |
| $f_{CLK}$  | Clock frequency                         |   |             |     | 400         | kHz           |

- (1) Limits are ensured. All electrical characteristics having room-temperature limits are tested during production with  $T_J = 25^\circ\text{C}$ . All hot and cold limits are ensured by correlating the electrical characteristics to process and temperature variations and applying statistical process control.
- (2) Each LED pin must not exceed 25 mA and each octal (LED0–LED7; LED8–LED15) must not exceed 100 mA. The package must not exceed a total of 200 mA.
- (3) Verified by design.

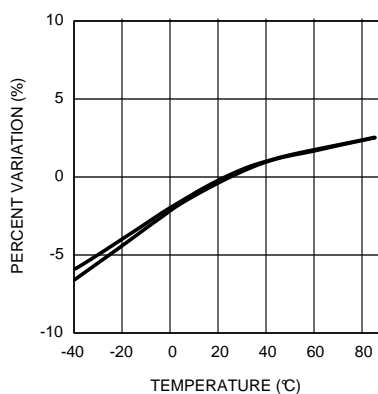
## 6.6 I<sup>2</sup>C Interface (SCL and SDA Pins) Timing Requirements

See <sup>(1)</sup>

|                        |  | MIN | NOM | MAX | UNIT |
|------------------------|--|-----|-----|-----|------|
| t <sub>HOLD</sub>      | Hold time repeated START condition   | 0.6 |     |     | μs   |
| t <sub>CLK-LP</sub>    | CLK low period   | 1.3 |     |     | μs   |
| t <sub>CLK-HP</sub>    | CLK high period  | 0.6 |     |     | μs   |
| t <sub>SU</sub>        | Setup time repeated START condition  | 0.6 |     |     | μs   |
| t <sub>DATA-HOLD</sub> | Data hold time   | 300 |     |     | ns   |
| t <sub>DATA-SU</sub>   | Data setup time  | 100 |     |     | ns   |
| t <sub>SU</sub>        | Setup time for STOP condition  | 0.6 |     |     | μs   |
| t <sub>TRANS</sub>     | Maximum pulse width of spikes that must be suppressed by the input filter of both DATA and CLK signals |     | 50  |     | ns   |

(1) All values verified by design.

## 6.7 Typical Characteristic



$$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C} \quad V_{DD} = 2.3 \text{ V to } 3 \text{ V}$$

**Figure 1. Frequency vs. Temperature**



### 7.3 Feature Description

Some of the features of the LP3943 device are:

1. 16 low-side switches to control the current in 16 strings of LEDs with a maximum of 25 mA per switch or a maximum of 200 mA total.
2. Programmable internal PWM dimming:
  - (a) Duty cycle control (8 bits). Any of the 16 current switches can be mapped to either PWM0 register or PWM1 register. Each register offers 8-bit PWM duty cycle control.
  - (b) PWM Frequency control (8 bits). Any of the 16 current switches can be mapped to either PSC0 register or PSC1 register. Each register offers 8-bit PWM frequency control from 0.625 Hz to 160 Hz.
3. RESET input.
4. Auto increment for I2C writes to reduce number of I2C clock pulses .
5. The LP3943 provides for an externally selectable I2C slave address via the ADR0, ADR1, and ADR2 inputs. See [Figure 4](#).

### 7.4 Device Functional Modes

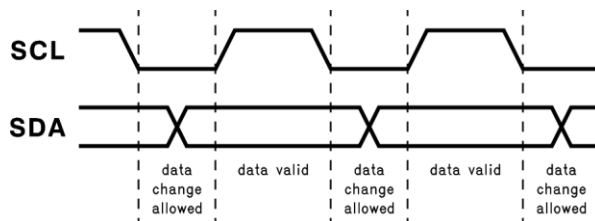
1. Output set to high impedance. This is set by programming bits [B0 and B1] to 00 in the LS0, LS1, LS2, or LS3 registers (see [Table 2](#))
2. Output set to ON state (current switch pulls low). This turns the LED on at the full current in the specified current switch bits [B0 and B1] set to 01 in the LS0, LS1, LS2, or LS3 registers (see [Table 12](#)).
3. Output set to toggle at the programmed PWM duty cycle and PWM frequency. This turns on or off the specified current switch at the programmed PWM frequency and duty cycle. Each current switch is mapped to either of the PWM0/PSC0 or PWM1/PSC1 pairs by setting [B0 and B1] to 10 or 11 in the LS0, LS1, LS2, or LS3 registers (see [Table 12](#)).



## 7.5 Programming

### 7.5.1 I<sup>2</sup>C Data Validity

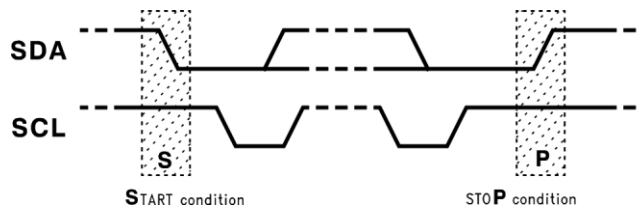
The data on SDA line must be stable during the HIGH period of the clock signal (SCL). In other words, state of the data line can only be changed when CLK is LOW.



**Figure 2. I<sup>2</sup>C Data Validity**

### 7.5.2 I<sup>2</sup>C START and STOP Conditions

START and STOP bits classify the beginning and the end of the I<sup>2</sup>C session. START condition is defined as SDA signal transitioning from HIGH to LOW while SCL line is HIGH. STOP condition is defined as the SDA transitioning from LOW to HIGH while SCL is HIGH. The I<sup>2</sup>C master always generates START and STOP bits. The I<sup>2</sup>C bus is considered to be busy after START condition and free after STOP condition. During data transmission, I<sup>2</sup>C master can generate repeated START conditions. First START and repeated START conditions are equivalent, function-wise.

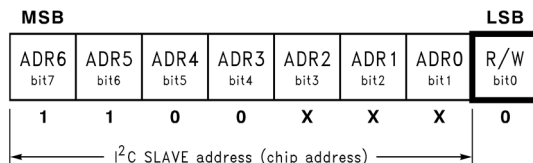


**Figure 3. I<sup>2</sup>C START and STOP Conditions**

### 7.5.3 Transferring Data

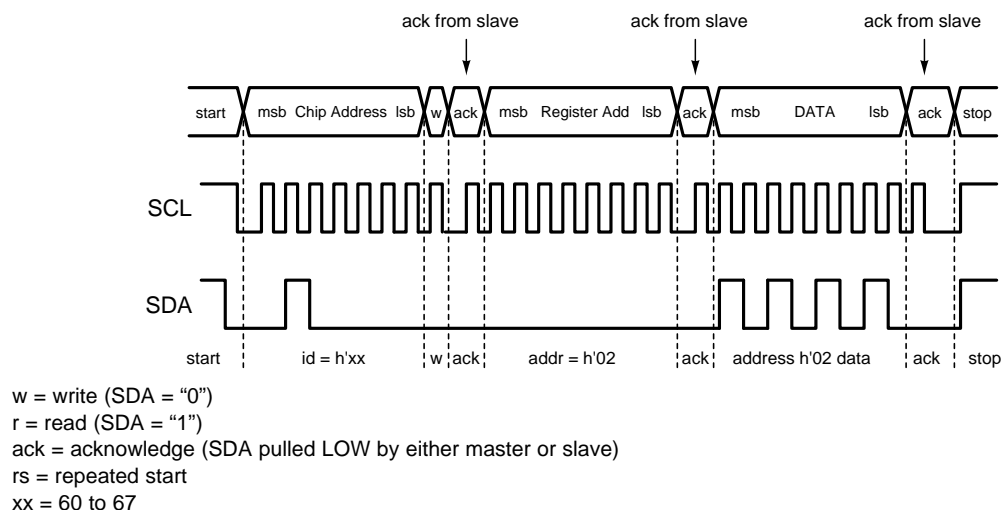
Every byte put on the SDA line must be eight bits long with the most significant bit (MSB) being transferred first. The number of bytes that can be transmitted per transfer is unrestricted. Each byte of data has to be followed by an acknowledge bit. The acknowledge related clock pulse is generated by the master. The transmitter releases the SDA line (HIGH) during the acknowledge clock pulse. The receiver must pull down the SDA line during the 9th clock pulse, signifying an acknowledge. A receiver which has been addressed must generate an acknowledge after each byte has been received.

After the START condition, a chip address is sent by the I<sup>2</sup>C master. This address is seven bits long followed by an eighth bit which is a data direction bit (R/W). The LP3943 hardwires bits 7 to 4 and leaves bits 3 to 1 selectable, as shown in Figure 4. For the eighth bit, a “0” indicates a WRITE and a “1” indicates a READ. The LP3943 supports only a WRITE during chip addressing. The second byte selects the register to which the data is written. The third byte contains data to write to the selected register.



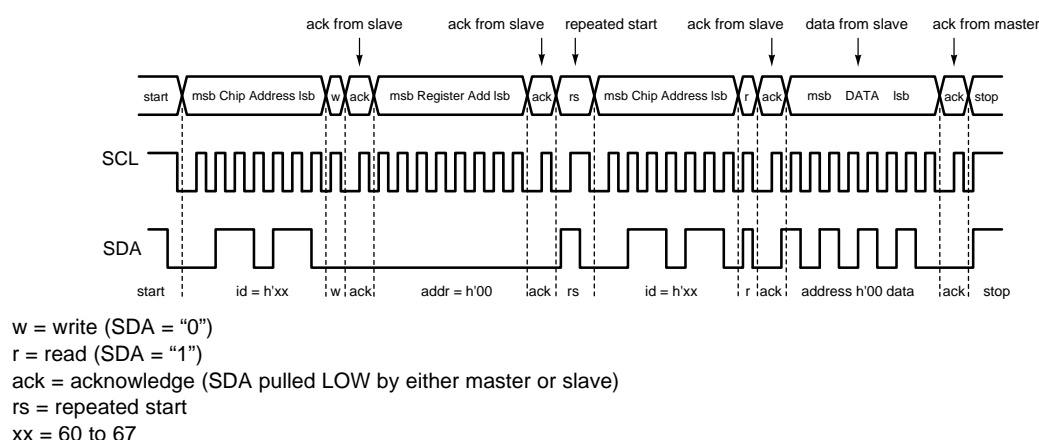
**Figure 4. Chip Address Byte**

## Programming (continued)



**Figure 5. LP3943 Register Write**

However, if a READ function is to be accomplished, a WRITE function must precede the READ function, as shown in [Figure 6](#).

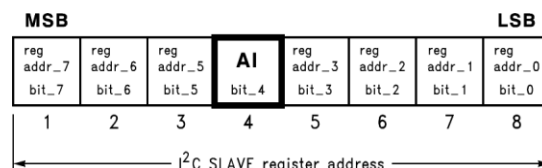


**Figure 6. LP3943 Register Read**

### 7.5.4 Auto Increment

Auto increment is a special feature supported by the LP3943 to eliminate repeated chip and register addressing when data are to be written to or read from registers in sequential order. The auto increment bit is inside the register address byte, as shown in [Figure 7](#). Auto increment is enabled when this bit is programmed to "1" and disabled when it is programmed to "0".

Bits 5, 6 and 7 in the register address byte must always be zero.



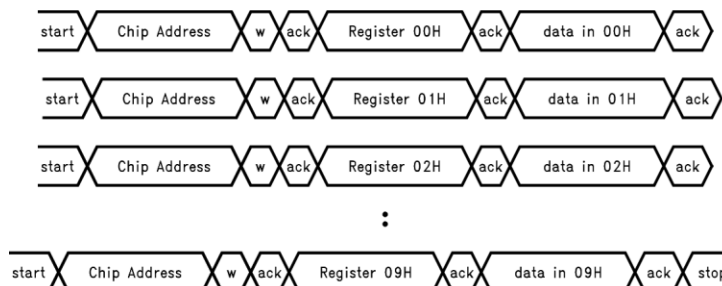
**Figure 7. Register Address Byte**

## Programming (continued)

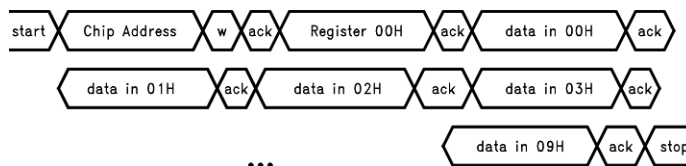
In the READ mode, when auto increment is enabled, I<sup>2</sup>C master could receive any number of bytes from LP3943 without selecting chip address and register address again. Every time the I<sup>2</sup>C master reads a register, the LP3943 increments the register address, and the next data register is read. When I<sup>2</sup>C master reaches the last register (09H), the register address rolls over to 00H.

In the WRITE mode, when auto increment is enabled, the LP3943 increments the register address every time I<sup>2</sup>C master writes to register. When the last register (09H register) is reached, the register address rolls over to 02H, not 00H, because the first two registers in LP3943 are read-only registers. It is possible to write to the first two registers independently, and the LP3943 device will acknowledge, but the data is ignored.

If auto increment is disabled, and the I<sup>2</sup>C master does not change register address, it continues to write data into the same register.



**Figure 8. Programming With Auto Increment Disabled (in WRITE Mode)**



**Figure 9. Programming With Auto Increment Enabled (in WRITE Mode)**

## 7.6 Register Maps

**Table 1. LP3943 Register Table**

| Address (Hex) | Register Name | Read/Write | Register Function      |
|---------------|---------------|------------|------------------------|
| 0x00          | Input 1       | Read Only  | LED0–7 Input Register  |
| 0x01          | Input 2       | Read Only  | LED8–15 Input Register |
| 0x02          | PSC0          | R/W        | Frequency Prescaler 0  |
| 0x03          | PWM0          | R/W        | PWM Register 0         |
| 0x04          | PSC1          | R/W        | Frequency Prescaler 1  |
| 0x05          | PWM1          | R/W        | PWM Register 1         |
| 0x06          | LS0           | R/W        | LED0–3 Selector        |
| 0x07          | LS1           | R/W        | LED4–7 Selector        |
| 0x08          | LS2           | R/W        | LED8–11 Selector       |
| 0x09          | LS3           | R/W        | LED12–15 Selector      |

### 7.6.1 Binary Format for Input Registers (Read-only)—Address 0x00 and 0x01

**Table 2. Address 0x00**

| Bit #         | 7    | 6    | 5    | 4    | 3    | 2    | 1    | 0    |
|---------------|------|------|------|------|------|------|------|------|
| Default value | X    | X    | X    | X    | X    | X    | X    | X    |
|               | LED7 | LED6 | LED5 | LED4 | LED3 | LED2 | LED1 | LED0 |

**Table 3. Address 0x01**

| Bit #         | 7     | 6     | 5     | 4     | 3     | 2     | 1    | 0    |
|---------------|-------|-------|-------|-------|-------|-------|------|------|
| Default value | X     | X     | X     | X     | X     | X     | X    | X    |
|               | LED15 | LED14 | LED13 | LED12 | LED11 | LED10 | LED9 | LED8 |

### 7.6.2 Binary Format for Frequency Prescaler and PWM Registers — Address 0x02 to 0x05

**Table 4. Address 0x02 (PSC0)**

| Bit #         | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------------|---|---|---|---|---|---|---|---|
| Default value | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

**Table 5. Address 0x03 (PWM0)**

| Bit #         | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------------|---|---|---|---|---|---|---|---|
| Default value | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

**Table 6. Address 0x04 (PSC1)**

| Bit #         | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------------|---|---|---|---|---|---|---|---|
| Default value | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

**Table 7. Address 0x05 (PWM1)**

| Bit #         | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---------------|---|---|---|---|---|---|---|---|
| Default value | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

### 7.6.3 Binary Format for Selector Registers — Address 0x06 to 0x09

**Table 8. Address 0x06 (LS0)**

| Bit #         | 7    | 6  | 5    | 4  | 3    | 2  | 1    | 0  |
|---------------|------|----|------|----|------|----|------|----|
| Default value | 0    | 0  | 0    | 0  | 0    | 0  | 0    | 0  |
|               | B1   | B0 | B1   | B0 | B1   | B0 | B1   | B0 |
|               | LED3 |    | LED2 |    | LED1 |    | LED0 |    |

**Table 9. Address 0x07 (LS1)**

| Bit #         | 7    | 6  | 5    | 4  | 3    | 2  | 1    | 0  |
|---------------|------|----|------|----|------|----|------|----|
| Default value | 0    | 0  | 0    | 0  | 0    | 0  | 0    | 0  |
|               | B1   | B0 | B1   | B0 | B1   | B0 | B1   | B0 |
|               | LED7 |    | LED6 |    | LED5 |    | LED4 |    |

**Table 10. Address 0x08 (LS2)**

| Bit #         | 7     | 6  | 5     | 4  | 3    | 2  | 1    | 0  |
|---------------|-------|----|-------|----|------|----|------|----|
| Default value | 0     | 0  | 0     | 0  | 0    | 0  | 0    | 0  |
|               | B1    | B0 | B1    | B0 | B1   | B0 | B1   | B0 |
|               | LED11 |    | LED10 |    | LED9 |    | LED8 |    |

**Table 11. Address 0x09 (LS3)**

| Bit #         | 7     | 6  | 5     | 4  | 3     | 2  | 1     | 0  |
|---------------|-------|----|-------|----|-------|----|-------|----|
| Default value | 0     | 0  | 0     | 0  | 0     | 0  | 0     | 0  |
|               | B1    | B0 | B1    | B0 | B1    | B0 | B1    | B0 |
|               | LED15 |    | LED14 |    | LED13 |    | LED12 |    |

**Table 12. LED States With Respect To Values in B1 and B0**

| B1 | B0 | Function                |
|----|----|-------------------------|
| 0  | 0  | Output Hi-Z (LED off)   |
| 0  | 1  | Output LOW (LED on)     |
| 1  | 0  | Output dims (DIM0 rate) |
| 1  | 1  | Output dims (DIM1 rate) |

## LP3943

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### Programming Example:

- Dim LEDs 0 to 7 at 1 Hz at 25% duty cycle
- Dim LEDs 8 to 12 at 5 Hz at 50% duty cycle
- Set LEDs 13, 14 and 15 off
- Step 1: Set PSC0 to achieve DIM0 of 1 s
- Step 2: Set PWM0 duty cycle to 25%
- Step 3: Set PSC1 to achieve DIM1 of 0.2 s
- Step 4: Set PWM1 duty cycle to 50%
- Step 5: Set LEDs 13, 14 and 15 off by loading the data into LS3 register
- Step 6: Set LEDs 0 to 7 to point to DIM0
- Step 7: Set LEDs 8 to 12 to point to DIM1

**Table 13. Programming Details**

| STEP | DESCRIPTION   | REGISTER NAME | SET TO (HEX)             |
|------|---|---------------|--------------------------|
| 1    | Set DIM0 = 1 s<br>$1 = (\text{PSC0} + 1)/160$<br>PSC0 = 159   | PSC0          | 0x09F                    |
| 2    | Set duty cycle to 25%<br>Duty Cycle = PWM0/256<br>PWM0 = 64   | PWM0          | 0x40                     |
| 3    | Set DIM1 = 0.2s<br>$0.2 = (\text{PSC1} + 1)/160$<br>PSC1 = 31 | PSC1          | 0x1F                     |
| 4    | Set duty cycle to 50%<br>Duty Cycle = PWM1/256<br>PWM1 = 128  | PWM1          | 0x80                     |
| 5    | LEDs 13, 14 and 15 off<br>Output = HIGH                       | LS3           | 0x03                     |
| 6    | LEDs 0 to 7<br>Output = DIM0                                  | LS0, LS1      | LS0 = 0xAA<br>LS1 = 0xAA |
| 7    | LEDs 8 to 12<br>Output = DIM1                                 | LS2, LS3      | LS2 = 0xFF<br>LS3 = 0x03 |

## 8 Application and Implementation

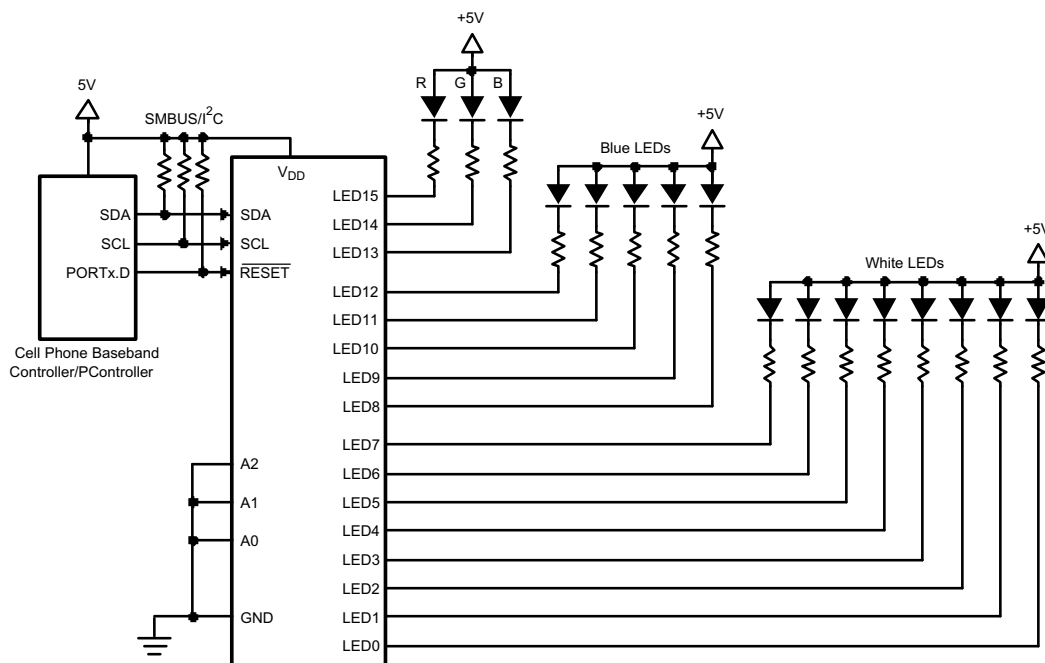
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The LP3943 is a 16-channel LED controller which has 16 low-side current switches. Each switch can control the LED current in its respective LED or LEDs by modulating its duty cycle and frequency.

### 8.2 Typical Application



**Figure 10. LP3943 Typical Application**

#### 8.2.1 Design Requirements

For typical RGB LED light-driver applications, use the parameters listed in [Table 14](#).

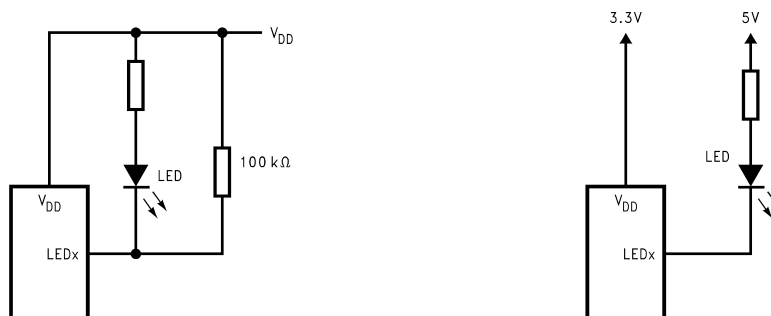
**Table 14. Design Parameters**

| DESIGN PARAMETER       | EXAMPLE VALUE |
|------------------------|---------------|
| Minimum input voltage  | 2.3 V         |
| Typical output voltage | 5 V           |
| Output current         | 20 mA         |

## 8.2.2 Detailed Design Procedure

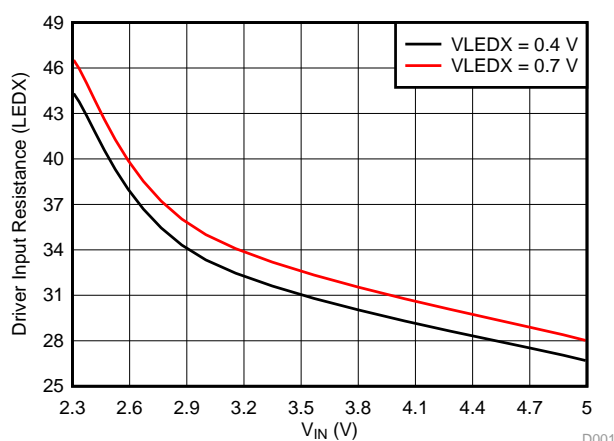
### 8.2.2.1 Reducing $I_Q$ When LEDs are OFF

In many applications, the LEDs and the LP3943 share the same  $V_{DD}$ , as shown in Figure 10. When the LEDs are off, the LED pins are at a lower potential than  $V_{DD}$ , causing extra supply current ( $\Delta I_Q$ ). To minimize this current, consider keeping the LED pins at a voltage equal to or greater than  $V_{DD}$ .



**Figure 11. Methods to Reduce  $I_Q$  When LEDs are in OFF State**

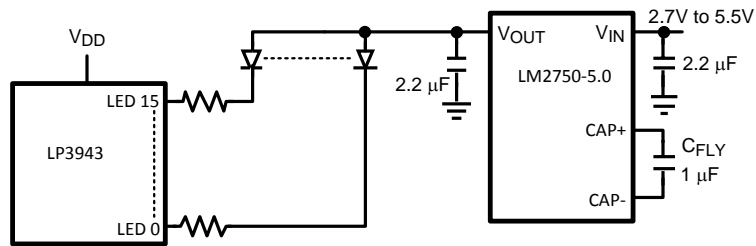
## 8.2.3 Application Curve



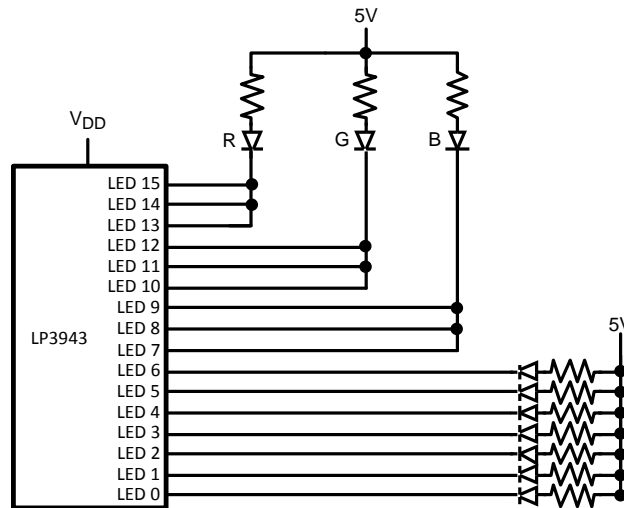
**Figure 12. Typical LED Switch Resistance**



### 8.3 System Examples



**Figure 13. LP3943 With 5-V Booster**



**Figure 14. LP3943 Driving RGB LED as a Flash**

## 9 Power Supply Recommendations

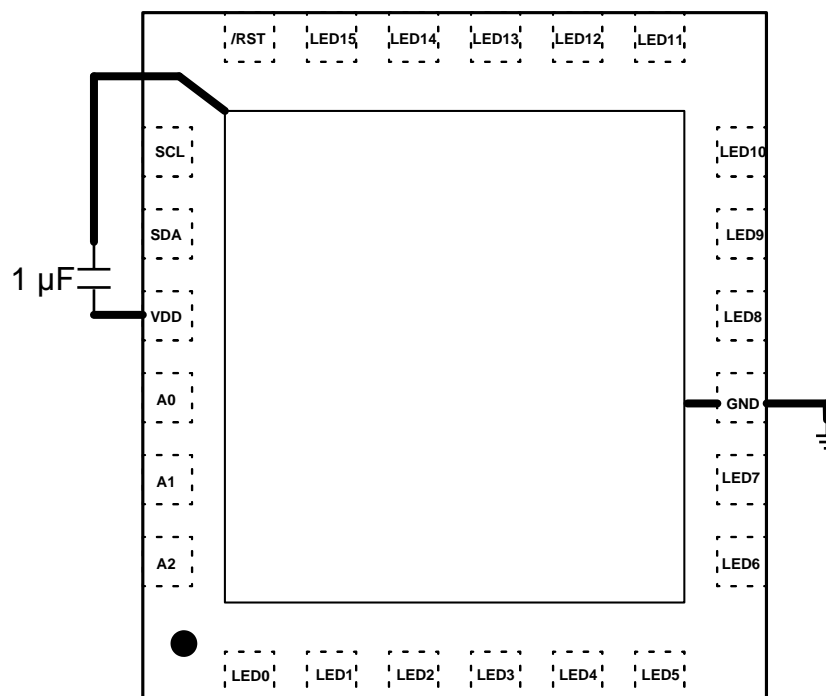
The LP3943 is designed to be powered from a 2.3-V minimum to a 5.5-V maximum supply input.

## 10 Layout

### 10.1 Layout Guidelines

The LP3943 layout is not critical, but it is recommended to provide a noise-free supply input at  $V_{DD}$ . This typically would require a 1- $\mu$ F capacitor placed close to the VDD pin and ground.

### 10.2 Layout Example



**Figure 15. LP3943 Layout Example**

## 11 Device and Documentation Support

### 11.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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### 11.2 Trademarks

E2E is a trademark of Texas Instruments.  
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### 11.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| LP3943ISQ        | NRND          | WQFN         | RTW                | 24   | 1000           | TBD                        | Call TI                 | Call TI              | -40 to 85    | 3943SQ                  |                         |
| LP3943ISQ/NOPB   | ACTIVE        | WQFN         | RTW                | 24   | 1000           | Green (RoHS<br>& no Sb/Br) | CU SN                   | Level-1-260C-UNLIM   | -40 to 85    | 3943SQ                  | <a href="#">Samples</a> |
| LP3943ISQX/NOPB  | ACTIVE        | WQFN         | RTW                | 24   | 4500           | Green (RoHS<br>& no Sb/Br) | CU SN                   | Level-1-260C-UNLIM   | -40 to 85    | 3943SQ                  | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

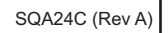
| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LP3943ISQ       | WQFN         | RTW             | 24   | 1000 | 178.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |
| LP3943ISQ/NOPB  | WQFN         | RTW             | 24   | 1000 | 178.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |
| LP3943ISQX/NOPB | WQFN         | RTW             | 24   | 4500 | 330.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LP3943ISQ       | WQFN         | RTW             | 24   | 1000 | 210.0       | 185.0      | 35.0        |
| LP3943ISQ/NOPB  | WQFN         | RTW             | 24   | 1000 | 210.0       | 185.0      | 35.0        |
| LP3943ISQX/NOPB | WQFN         | RTW             | 24   | 4500 | 367.0       | 367.0      | 35.0        |





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